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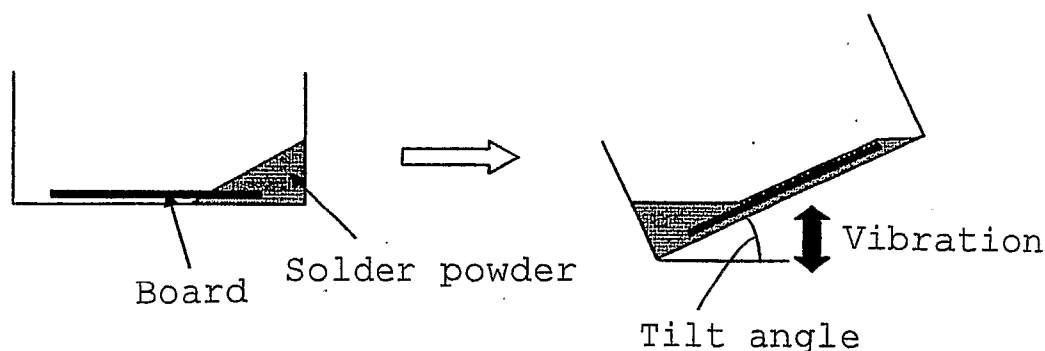
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(54) Title: PRODUCTION METHOD OF SOLDER CIRCUIT BOARD



(57) Abstract: A method for producing a solder circuit board includes imparting tackiness to a surface of a conductive circuit electrode provided on a printed wiring board to form a tackiness-imparted area. depositing solder powder on the tackiness-imparted area and heating the printed wiring board so as to melt the solder to thereby form a solder circuit. The solder powder is placed in a vessel. The printed wiring board having the electrode whose surface has been imparted with tackiness is placed in the vessel. The vessel is tilted to thereby deposit the solder powder on the tackiness-imparted area.

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